



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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Hardware Features

Chip Type

Supplier
Chip Codes
Electrical Characteristics
Operational Temperature Characteristics
Memory Size available for program and data

Industrial Grade

Starchip
SCM392G
1.6V to 5.5V
-40° to 105°C
136K/256K

Standard Grade

Samsung
S3FS9FG
1.6V, 3V and 5V
-25° to 85°C
340K/440K

NVRAM characteristics

Endurance cycles (min) @ 25°	Min. 200MM read/write cycle	Min. 500K read/write cycle
Data retention (min) @ 25°	25 Years	25 Years
Vibration	Passes JESD22-B103	
Sector/Bank erase time	1.5ms/3ms	1.5ms/3ms
Page write/erase time	1.5ms/0.4ms	1.5ms/0.4ms

Software Features

Platform

Technology	2G/3G/4G/LTE	2G/3G/4G/LTE
UICC	Release 8	Release 8
Java Card	2.2.1 or higher	2.2.1 or higher
Global Platform	2.2.1	2.2.1

Supported Applications

SIM	Release 4	Release 4
USIM	Release 8	Release 8
ISIM	Release 8	Release 8
HPSIM	Release 8	

OTA Capabilities

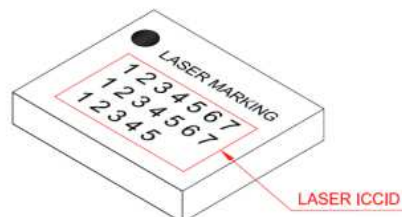
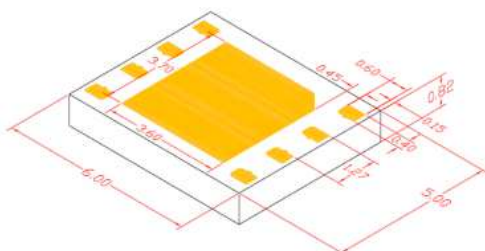
Remote File Management	Release 8	Release 8
Remote Applet Management	Release 8	Release 8

SIM Card Physical Characteristics

Embedded Form Factor (MFF2)

Module Format	MFF2 (QFN8) embedded.
Size	6 x 5mm*, (height: 0.75-0.82mm)
Standard	TS 102.671 - standardized format
Fitting	Soldered to circuit board
Transportation	On trays/reels/boxes

Technical Details (MFF2)



SIM Card Physical Characteristics



2FF - Mini SIM

Height: 25mm
Width: 15mm
Thickness: 0.76mm



3FF - Micro SIM

Height: 15mm
Width: 12mm
Thickness: 0.76mm



4FF - Nano SIM

Height: 12.3mm
Width: 8.8mm
Thickness: 0.67mm

Embedded SIM QNF8 Pinout

